

### GENERAL DESCRIPTION

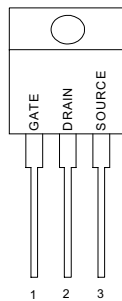
This Power MOSFET is designed for low voltage, high speed power switching applications such as switching regulators, converters, solenoid and relay drivers.

### FEATURES

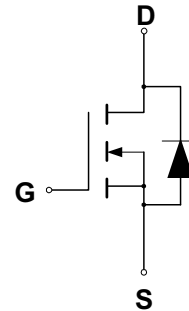
- ◆ Higher Current Rating
- ◆ Lower  $r_{DS(ON)}$ , Lower Capacitances
- ◆ Lower Total Gate Charge
- ◆ Tighter VSD Specifications
- ◆ Avalanche Energy Specified

### PIN CONFIGURATION

TO-220/TO-220FP  
Top View



### SYMBOL



N-Channel MOSFET

### ORDERING INFORMATION

Part Number	Package
IRF830	TO-220
IRF830FP	TO-220FP

### ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain to Current — Continuous	$I_D$	5.0	A
— Pulsed (Note 1)	$I_{DM}$	18	
Gate-to-Source Voltage — Continue	$V_{GS}$	±20	V
Total Power Dissipation	$P_D$	96	W
Derate above 25°C		0.77	W/°C
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	125	mJ
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C
Thermal Resistance — Junction to Case	$\theta_{JC}$	1.70	°C/W
— Junction to Ambient	$\theta_{JA}$	62	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	$T_L$	300	°C

### ELECTRICAL CHARACTERISTICS

Unless otherwise specified,  $T_J = 25^\circ\text{C}$ .

Characteristic	Symbol	IRF830			Units
		Min	Typ	Max	
Drain-Source Breakdown Voltage ( $V_{GS} = 0\text{ V}$ , $I_D = 250\ \mu\text{A}$ )	$V_{(BR)DSS}$	500			V
Drain-Source Leakage Current ( $V_{DS} = 500\text{V}$ , $V_{GS} = 0\text{ V}$ )	$I_{DSS}$			25	$\mu\text{A}$
Gate-Source Leakage Current-Forward ( $V_{gsf} = 20\text{ V}$ , $V_{DS} = 0\text{ V}$ )	$I_{GSSF}$			100	nA
Gate-Source Leakage Current-Reverse ( $V_{gsr} = -20\text{ V}$ , $V_{DS} = 0\text{ V}$ )	$I_{GSSR}$			-100	nA
Gate Threshold Voltage ( $V_{DS} = V_{GS}$ , $I_D = 250\ \mu\text{A}$ )	$V_{GS(th)}$	2.0		4.0	V
Static Drain-Source On-Resistance ( $V_{GS} = 10\text{ V}$ , $I_D = 2.7\text{A}$ ) (Note 3)	$R_{DS(on)}$			1.5	$\Omega$
Forward Transconductance ( $V_{DS} = 15\text{V}$ , $I_D = 2.5\text{ A}$ ) (Note 3)	$g_{FS}$	2.8			mhos
Input Capacitance	$(V_{DS} = 25\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1.0\text{ MHz}$ )	$C_{iss}$	520	730	pF
Output Capacitance		$C_{oss}$	170	240	pF
Reverse Transfer Capacitance		$C_{rss}$	11	20	pF
Turn-On Delay Time	$(V_{DD} = 250\text{ V}$ , $I_D = 5\text{ A}$ , $R_G = 9.1\Omega$ , $V_{GS} = 10\text{ V}$ ) (Note 3)	$t_{d(on)}$	7.0	10	ns
Rise Time		$t_r$	9.0	20	ns
Turn-Off Delay Time		$t_{d(off)}$	20	40	ns
Fall Time		$t_f$	10	20	ns
Total Gate Charge	$(V_{DS} = 400\text{V}$ , $I_D = 5\text{ A}$ , $V_{GS} = 10\text{ V}$ ) (Note 3)	$Q_g$	10		nC
Gate-Source Charge		$Q_{gs}$	2		nC
Gate-Drain Charge		$Q_{gd}$	3		nC
Internal Drain Inductance (Measured from the drain lead 0.25" from package to center of die)	$L_D$		4.5		nH
Internal Drain Inductance (Measured from the source lead 0.25" from package to source bond pad)	$L_S$		7.5		nH
<b>SOURCE-DRAIN DIODE CHARACTERISTICS</b>					
Reverse Recovery Charge	$I_F = 5\text{ A}$ , $di/dt = 100\text{A}/\mu\text{s}$ , $T_J = 25^\circ\text{C}$	$Q_{rr}$		1.8	$\mu\text{C}$
Forward Turn-On Time		$t_{on}$		**	
Reverse Recovery Time		$t_{rr}$		415	
Diode Forward Voltage	$I_S = 5\text{ A}$ , $V_{GS} = 0\text{ V}$	$V_{SD}$		1.5	V

**Note**

- (1) Repetitive rating; pulse width limited by max. junction temperature
- (2)  $V_{DD} = 100\text{V}$ ,  $V_{GS} = 10\text{V}$ ,  $L = 10\text{mH}$ ,  $I_{AS} = 5\text{A}$ ,  $R_G = 25\Omega$
- (3) Pulse Test: Duty Cycle  $\leq 2\%$ , Pulse Width  $\leq 300\mu\text{s}$
- \*\* Negligible, Dominated by circuit inductance

TYPICAL ELECTRICAL CHARACTERISTICS

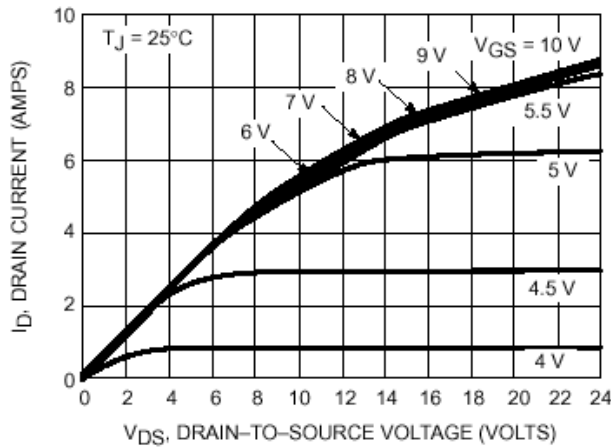


Figure 1. On-Region Characteristics

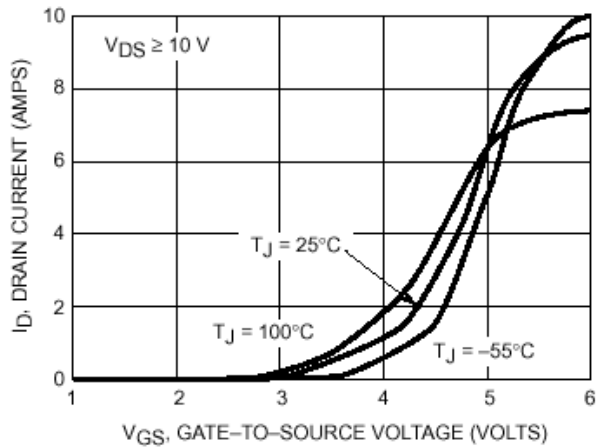


Figure 2. Transfer Characteristics

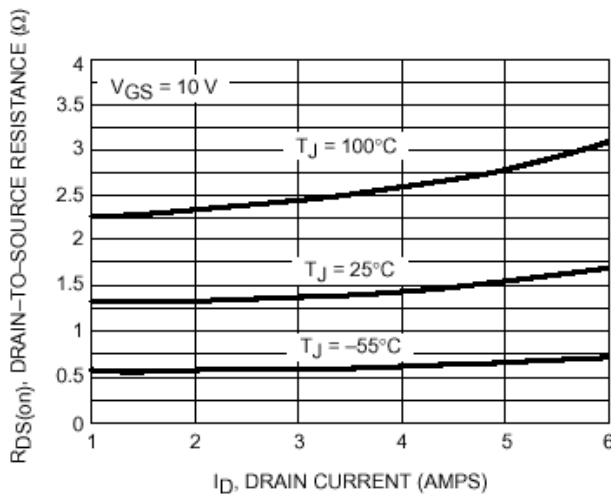


Figure 3. On-Resistance versus Drain Current and Temperature

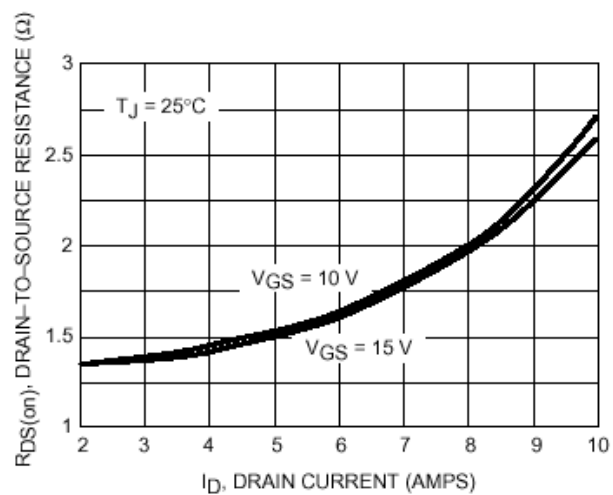


Figure 4. On-Resistance versus Drain Current and Gate Voltage

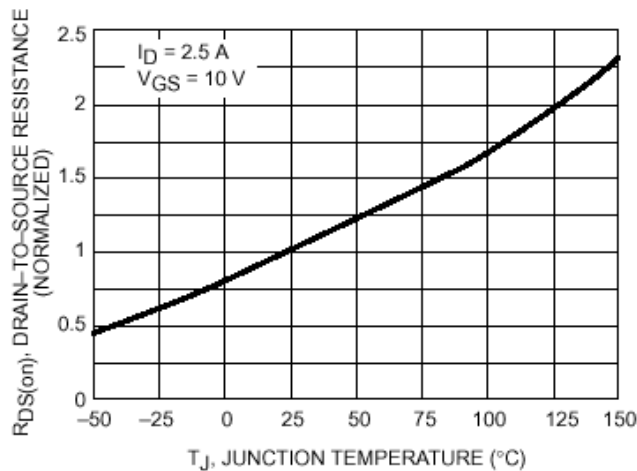


Figure 5. On-Resistance Variation with Temperature

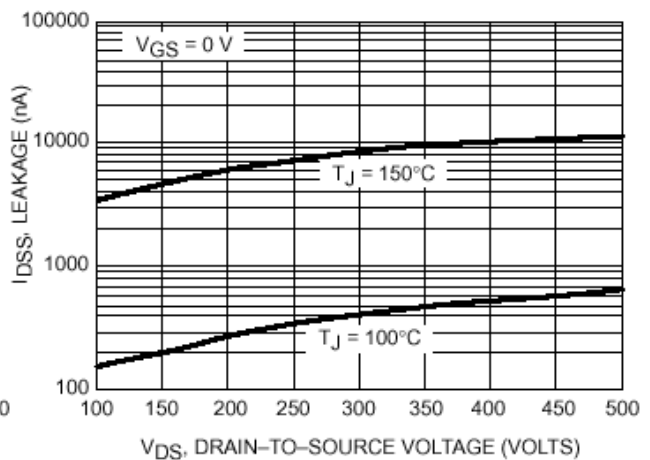


Figure 6. Drain-to-Source Leakage Current versus Voltage

PACKAGE DIMENSION

